

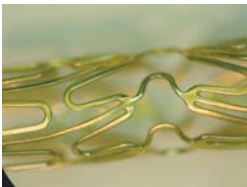
PJ Plasma Surface Treatment System

The PJ Plasma Surface Treatment System is a compact, user-friendly tool with all the functionality of our large batch gas plasma systems. Designed for both laboratory and production use, the PJ is versatile and can be used for a variety of plasma-based processes including cross linking and cleaning organic or inorganic contamination from various substrates such as: metals, ceramics, glass, and silicon. It is also ideal for improving lubricity, wettability, and bond strength. Common applications include medical devices, RGP contact lenses, printed circuit boards and electronics. The entire unit conveniently fits in a single cabinet. Choose from Pyrex (standard), quartz, or aluminum chamber materials.

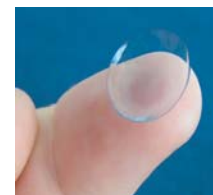


Notebook PC optional

Common Applications



Surface cleaning of stents



Enhance wettability of contact lenses



Surface modification of wellplates

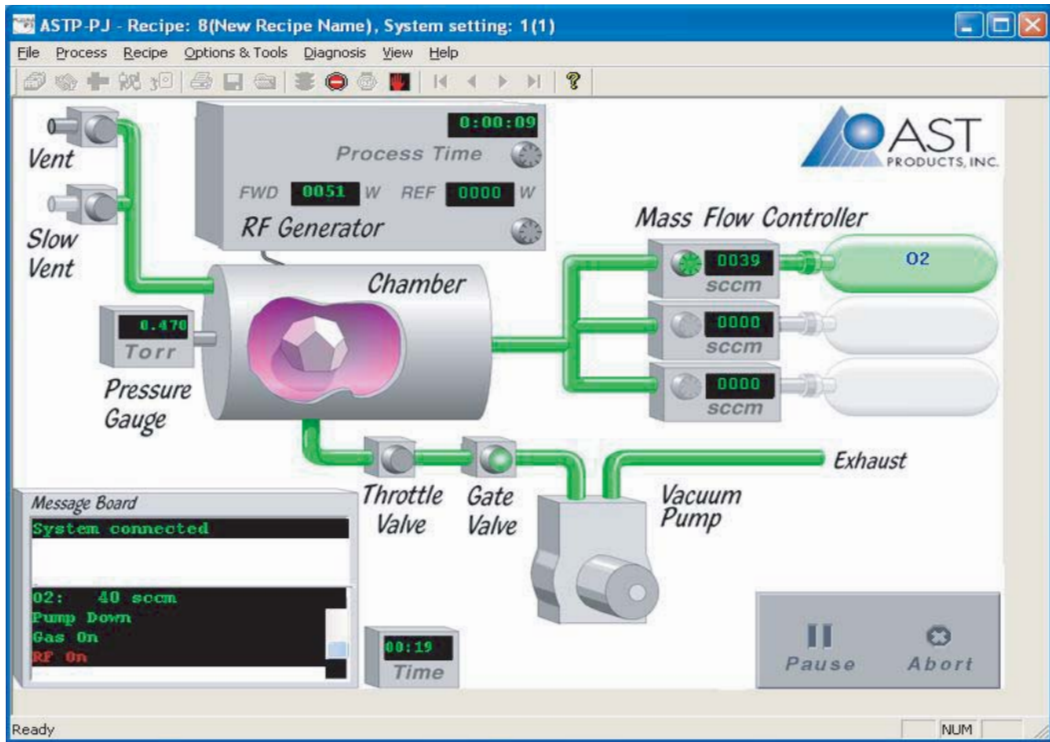
Plasma Surface Treatment

Plasma is a highly energized state of matter that consists of electrons, positive ions and neutral species. Feed gases are ionized at pressures at or below 200 mTorr to yield highly reactive species. These discrete plasmas can etch a surface, deposit a film, add or modify chemical functional groups or simply alter the surface energy to control water management characteristics. Low-temperature plasmas, also called cold plasmas, do not adversely affect the bulk properties of polymers, metal alloys, glasses and ceramics. Instead the effect is realized at the surface to provide new and enhanced surface functionality.



Contact angle measurements of an RGP contact lens before and after plasma treatment.*

* Contact angle measurements taken with AST Products' VCA Optima XE Surface Analysis System. Visit www.astp.com/vca/vca_optima.html for more information on our video contact angle analysis equipment.



The PJ's main user interface screen constantly displays all the key process information in real time. Information such as RF forward and reflective power, gas flow, operating pressure and process time are all clearly displayed. A message board also displays the latest process function. Operators can choose from an infinite number of pre-programmed processes or create a new recipe. All parameters can be modified in-process from this main screen.

Main RF Power	115 VAC, 15 amp 300W 13.56 MHz	Gas Feed Options	One MFC included Choice of chamber material (quartz, or aluminum)
RF Match	Automatch		Pump filtration system
Control	Windows™ based Dell™ PC		O2 service on pump
Physical Size	24" W x 24" L x 12" H, Weight 75 lbs.		Mist Filter on pump
Chamber	8" diameter, 10" depth		Capacitance Manometer
	Pyrex		Throttle Valve
	Capacitively coupled		Vacuum Pump, 11 cfm, 115v, 15 amp
			2nd MFC
			Notebook PC

Preventative Maintenance & Warranty Programs Available



9 Linnell Circle, Billerica, MA 01821
Phone 978-667-4500 | Fax 978-667-9778
www.astp.com

